

CEO MESSAGE

Makoto Hattori

Representative Director
President, CEO and COO

We will forge ahead with determination to continuously raise corporate value, with the resolution of social issues and pursuit of rapid growth as driving forces.

Responsibility to Resolve Social Issues

LINTEC began its business by manufacturing gummed tape that could be applied with water, similar to postage stamps, and has now developed products in a wide range of areas as a comprehensive manufacturer of adhesive-related products. While we continue to adapt our products in line with changes in the business environment as well as people's lifestyles and the needs of customers, our fundamental role has not changed—to contribute to resolving social issues and consistently deliver the value required by customers through our adhesive-related products. I believe this is both LINTEC's mission and responsibility.

Looking solely at environmental issues, society is currently facing a wide range of problems that include reducing CO_2 emissions and realizing a circular society. More than ever, companies are being asked how they will address such issues while also determining how they will provide value. Meanwhile, as we are advancing efforts in our environmental response as a manufacturer, which include our work to enhance our lineup of environmentally friendly products, we are also participating in the Japan-Earth Conscious Labeling (J-ECOL), a label recycling association, to promote recycling of release paper across the entire label industry. As a result of these efforts, LINTEC's technologies and businesses are beginning to contribute to the resolution of social issues.

See the "Environment" section on page 55.

We are not only facing environmental issues. LINTEC's singular purpose entails contributing to resolving the social issues that lie beyond supporting our customers' industries and businesses. It is for this reason that I believe we must continue to be our customers' most important and strongest supporter.

Organizational Strength That Drives Our Value Creation

LINTEC's strengths lie in our high-variety, small-lot manufacturing that other companies find difficult to undertake, which is the result of carefully addressing the highly diverse needs and issues of each and every customer. In the process of striving to meet a wide range of requirements and specifications, ongoing dialogue with customers and daily collaboration between company divisions have become standard practice within our organization. By directly facing each issue through close coordination between our Sales, R&D, and Production divisions and bringing our ideas to life while sharing information and insights within the Company, we have cultivated the ability to accurately identify customer needs and to translate this knowledge into real solutions through technology. These are the source of LINTEC's value creation today.

At the root of this lies our highest priority—making connections with people. We have established strong and lasting partnerships with customers through our efforts to foster relationships and build trust over many years. Even when customers choose a competitor's product, we maintain our relationship with them, analyze any issues, and make continuous improvements, which has led to future opportunities. I firmly believe that this ability to sustain relationships is the very driving force of LINTEC's growth.

We share information and engage in rapid decision-making across divisions. These include not only Sales, R&D, and Production but also administrative functions, such as Procurement and

Quality Assurance. The strength of this ability to collaborate contributes to not only the speed of our development but also our ability to respond to customers, underpinning LINTEC's competitive edge. This stance embodies our company motto of "Sincerity and Creativity." Our commitment to always act in a manner that is true to our company motto remains unwavering, regardless of the business conditions. I firmly believe in the importance of building on our daily efforts, and this steady practice has fostered strong relationships and organizational capabilities, which have in turn led to our current business performance and corporate value.

Review of the Fiscal Year Ended March 31, 2026, and Outlook for the Fiscal Year Ending March 31, 2027

See the "Overview of Long-Term Vision LSV 2030" section on pages 14–15.

During the fiscal year ended March 31, 2026 (fiscal year under review), the second year of the medium-term business plan LSV 2030–Stage 2, net sales and operating income saw record highs for the second consecutive year. Being able to boost performance to this extent amid increasingly uncertain conditions is a testament to the unwavering efforts of all our employees.

See the "A Message from the CFO" section on pages 18–21.

We have been forging ahead with initiatives related to key themes of our long-term vision, LSV 2030, largely as planned. Under our structural reforms initiative, we have been optimizing our business portfolio through efforts that include the closure of our subsidiary LINTEC INDUSTRIES (MALAYSIA) and the shutting down of production equipment in the Fine & Specialty Paper Products Operations, while also actively engaging in measures such as introducing new production equipment through scrap and build. Regarding MACTAC AMERICAS, which is responsible for our North American label-related business, the amortization of planned goodwill has weighed on the company, preventing it from achieving the expected improvement in earnings, and we are addressing this as an urgent management issue. Numerous factors related to this issue are intertwined, such as the market environment in North America and various production systems, and resolving them requires time. However, we have been strengthening the support system from Japan, with measures that include optimizing production equipment and logistics bases. We are also beginning to see progress in improving yield rates, ensuring we achieve profitability at an early stage.

The semiconductor-related business, which is a growth field, is expanding at an unprecedented speed due to the rapidly increasing demand for AI, with performance that has greatly exceeded that of the previous fiscal year. Orders remained strong for not only semiconductor-related adhesive tape and multilayer ceramic capacitor-related tape, but also for equipment for semiconductor manufacturing, including tools for high-bandwidth memory (HBM) manufacturing. In the fiscal year ending March 31, 2027 (the current fiscal year), we will capitalize on this tailwind while steadily advancing initiatives aimed at the production of carbon nanotube (CNT) pellicles for extreme ultraviolet (EUV) lithography equipment. For our environmental initiatives, we have received Science Based Targets (SBT) certification. We are continuously working to reduce our greenhouse gas emissions and will further advance specific measures in line with business activities.

See the "Environment" section on pages 52–53.

The fiscal year under review saw the challenges of running a business become even greater under an extremely harsh external environment that included concerns over the procurement of naphtha-derived raw materials, following increasing tensions in the Middle East. Amid these challenges, we placed the highest priority on responsible supply to our customers. Centered on our Procurement Division, we ensured a stable supply of raw materials and were able to fulfill our commitment to deliver. Since we are a business that is easily affected by the external environment, we have consistently placed great importance on developing systems to address latent issues during normal times. As a result, we have equipped ourselves with the capability to respond flexibly and accurately, even in highly uncertain environments. This adaptability was not created overnight but rather a skill that has been cultivated over time, and we regard it as one of LINTEC's core strengths.

The fiscal year under review is a key year for steadily making improvements to our revenue structure while also advancing the enhancement of production equipment and R&D sites to

encourage growth. Furthermore, even if a field has matured, there is still plenty of room to create new products and business opportunities that contribute to resolving social issues. With a view to the next medium-term business plan, LSV 2030–Stage 3, we will steadily advance all the themes adopted under LSV 2030 and are making appropriate investment decisions in the necessary fields.

Growth Strategies for 2030

Looking at our current business portfolio, the majority of the Company's profits are underpinned by the Advanced Materials Operations, which is focused on developing semiconductor-related products. As demand for AI is rapidly growing in the semiconductor market, we anticipate growth in the medium to long term. Semiconductors will continue to play an indispensable part in society's evolution, even in 10 or 20 years. Active capital investment by semiconductor manufacturers is expected to continue in the future, and I am determined that we effectively capture this growth opportunity. However, pursuing growth and strengthening the soundness of our business portfolio must be conducted simultaneously. I firmly believe that engaging in improvements to profitability in the other five divisions outside the Advanced Materials Operations is a vital issue. With this in mind, I am committed to establishing a profit-based business structure, further strengthening our semiconductor-related business, and creating new engines for growth.

1. Transformation to a Profit-Oriented Structure

The Printing & Variable Information Products Operations accounts for a substantial share of our sales, and I believe that improving profitability in this segment will have a significant impact on the Company as a whole. In particular, the North American adhesive labels market represents a key growth area for us, and improving the profitability of MACTAC AMERICAS is an urgent priority. As one of the largest adhesive labels markets in the world, with growth expected to accompany population increases, North America is a critically important region for us. While moving quickly to improve profitability, we intend to grow earnings by leveraging synergies across the Group in technology and sales channels. In addition, although the Fine & Specialty Paper Products Operations conducts business in a challenging environment, it remains an important business that supports the supply of raw materials (base paper for release paper) for our adhesive products. Viewing our response to social issues as an opportunity for growth, we will continue to pursue necessary investments and reforms from a medium- to long-term value creation perspective, rather than judging performance solely by short-term growth rates.

See the "Transformation to a Profit-Oriented Structure" section on pages 22–23.

2. Expansion of the Semiconductor-Related Business

The growth of our semiconductor-related business is not just attributable to market conditions. Since developing UV curable dicing tape in 1986, we have continuously created products that anticipate our customers' needs. Underpinning this, as I mentioned earlier, is the trust we have built with our customers over many years, as well as our comprehensive capabilities to address challenges as one unified team, namely, drawing on the integrated strength of sales, R&D, and production. I believe it is this high level of customer trust and recognition that has driven our current growth.

Our CNT pellicles for EUV lithography equipment originated from carbon nanotube research and development conducted at our R&D center in Texas (United States), which opened in 2013. While pellicles were not the original research theme, their potential and market needs became clear as we continued our R&D efforts. We are now in the final stages of preparation for full-scale production. I am strongly determined to ensure that the steadfast efforts by everyone involved launch a successful business. Going forward, we will address challenges one by one, including maintaining quality while ensuring a stable supply and improving usability, such as handling characteristics, to drive continued adoption and market expansion. We opened the Tsukuba Innovative Creation Center in June 2026. This will accelerate our pellicle-related initiatives while steadily advancing the development of new applications that leverage our technology. We will turn this robust demand into sustainable improvements in business performance.

See the "Expansion of the Semiconductor-Related Business" section on pages 24–27.

3. Creation of New Growth Engines

See the "Creation of New Growth Engines" section on pages 28–29

While semiconductor- and electronic component-related products are currently in the spotlight, their life cycles will inevitably come to an end. As a result, I believe that it is imperative to be proactive in our response to new developments in the medium to long term. With this in mind, we are focusing on developing materials and processes aimed at becoming the next-generation de facto standard and creating solutions that contribute to the resolution of social issues, with a view to the continued growth of semiconductors. Despite differing progress in each theme, there are some fields that are starting to take off due to industry–academic collaboration and external co-creation, and we anticipate an increase in the scope of our business portfolio in the future.

In research and development, the Research & Development Division currently serves as the core, while the Business Administration Division is also advancing initiatives aimed at creating new products and businesses as well as promoting research themes under a cross-organization, Companywide approach. This system allows us to incorporate market needs into our development process at an early stage and accelerate the creation of new products and their commercialization.

To achieve LSV 2030, LINTEC has adopted a multifaceted growth strategy that involves addressing all themes with the potential to develop a compelling narrative, rather than focusing heavily on one particular field. At first glance, it may seem extremely inefficient to work on so many themes at once. However, I recognize that our business is structured in a way that creates value through the interaction between technology, customer relationships, and our supply system. As a result, simply optimizing a single area in isolation is unlikely to yield sufficient results.

The Board of Directors also continues to discuss the optimization of our business portfolio as a key priority from the perspective of overall optimization. We will enhance the effectiveness of our strategies and enhance corporate value by incorporating the objective and candid opinions of our outside directors, who are informed by their experience and industry expertise.

Strengthening the Foundation That Accelerates Growth (Human Capital, DX, and Governance)

See the "Human Resource Strategy" section on pages 46–47.

Human resources are the source of our growth. While the approach to talent development varies by country, region, and industry, we are advancing human capital development across the Group in a systematic manner. In particular, securing and developing R&D talent is a critical issue that will determine our future competitiveness, and we are strengthening recruitment and development efforts in line with the expansion of our R&D themes. In addition, with overseas sales now accounting for more than 60% of total revenue, developing talent and strengthening governance at our overseas subsidiaries have become important management issues. Senior managers at our local operations are required to understand and apply both Japanese corporate philosophy and local management practices. We will steadily advance this talent development while further strengthening trust and governance within our local operations through ongoing communication and personnel exchanges.

See the "DX Strategy" section on pages 48–49.

One area that we are particularly focused on accelerating is the promotion of digital transformation (DX). We have positioned DX as an essential means of sustainably enhancing our competitiveness. The promotion of DX is not limited to specific departments, but rather a Companywide initiative encompassing all departments. In the previous fiscal year, we obtained DX Certification from Japan's Ministry of Economy, Trade and Industry. Building on the DX learning and infrastructure development we have focused on over the past several years, and incorporating external expertise in the process, we have now moved into the utilization and application phase, working to generate concrete results across our operations. In particular, advances in AI are bringing significant change to the speed of business execution across our operations. The speed of literature research and design review in our R&D operations is being substantially improved through the use

of AI. Rapid information sharing, decision-making, and development speed have long been among our strengths, and I believe DX will enable us to elevate these strengths even further. In this sense, DX is not merely a tool for improving operational efficiency. It is a critical initiative for further enhancing the Companywide agility that is one of our core strengths, and for driving new value creation. Through the development of DX talent and the use of data to enhance visibility and governance across the Group, we will work to build a more resilient management foundation on a global scale.

To Our Stakeholders

Guided by our company motto of "Sincerity and Creativity," we will continue to fulfill our corporate mission of resolving social issues by enhancing the resilience of our management foundation and business foundation, linking these efforts with solid business results. I believe that we must pursue both the resolution of social issues and rapid growth by working together as a company.

Our growth to date is entirely due to the understanding and support of our stakeholders. We will continue to meet our customers' expectations by providing value that exceeds those expectations, building on the foundation of trust with our customers. Corporate value is not evaluated on its short-term results. I firmly believe that it is viewed in terms of the efforts built up over 10 or 20 years.

LINTEC will continue to be our customers' most important and strongest supporter, and we will strive to sustainably enhance our corporate value through the pursuit of both social issue resolution and rapid growth. I sincerely ask for your continued understanding and support as we move ahead with these efforts.

Makoto Hattori
Representative Director
President, CEO and COO



Overview of Long-Term Vision LSV 2030

The LINTEC Group has formulated LINTEC SUSTAINABILITY VISION 2030 (LSV 2030), a long-term vision that continues through the fiscal year ending March 31, 2030, in the aim of realizing a sustainable society. With the basic approach of helping to resolve social issues through our business activities, we will actively address each key initiative from the perspective of sustainability.

LSV 2030
LINTEC SUSTAINABILITY VISION

Basic Policy

Contribute to realizing a sustainable world by strengthening the corporate structure through innovation and creating new products and businesses for sustainable growth

Key Initiatives

1 Solve social issues

(1) Environment
- Help to shape a carbon-free world
- Help to shape a recycling-oriented world
- Comply with the PRTR Act
- Contribute to biodiversity preservation initiatives

(2) Society
- Respect human rights
- Provide proper information disclosure to stakeholders
- Promote work-style reform initiatives
- Promote the quality-first and customer-first approaches

(3) Governance
- Strengthen corporate governance
- Further increase effectiveness of the Board of Directors
- Ensure the timely disclosure of corporate information and the transparency of management
- Engage in constructive dialogue with stakeholders and investors

(4) Ensure that business activities help to achieve the Sustainable Development Goals (SDGs)

2 Foster innovation to build a robust corporate structure

(1) Transform business processes including design, development, manufacturing, and logistics through digital transformation (DX)

(2) Install new production equipment through scrap and build, with the aim to conserve energy, raise quality, increase efficiency, and reduce labor

(3) Strengthen cost competitiveness with innovation in production processes

(4) Reform the structure of low-growth and unprofitable businesses and soundly manage Group companies

(5) Maintain a solid financial base and improve capital efficiency

3 Create new products and businesses to deliver sustainable growth

(1) Create new products and businesses driven by technological innovation

(2) Expand strategic investment and flexibly conduct mergers and acquisitions (M&A)

(3) Move aggressively to win a greater presence in the global market

(4) Establish localization

	Results for the Fiscal Year Ended March 31, 2025	Results for the Fiscal Year Ended March 31, 2026	Forecast for the Fiscal Year Ending March 31, 2027	Targets for the Fiscal Year Ending March 31, 2027*
Net Sales	¥316.0 billion	¥319.4 billion	**¥342.0 billion**	¥315.0 billion
Operating Income	¥24.6 billion	¥25.2 billion	**¥27.5 billion**	¥25.5 billion
Profit Attributable to Owners of Parent	¥14.5 billion	¥17.4 billion	**¥19.5 billion**	¥18.0 billion
Operating Profit Margin	7.8%	7.9%	—	8% or more
Return on Equity (ROE)	6.1%	6.9%	—	8% or more

* At the time of announcing the medium-term business plan LSV 2030-Stage 2 in March 2024

Stage 1
April 2021 to March 2024

Our Desired State

LSV 2030
LINTEC SUSTAINABILITY VISION

Operating Profit Margin
12% or more

Return on Equity (ROE)
10% or more

Stage 3
April 2027 to March 2030

Medium-Term Business Plan Stage 2

April 2024 to March 2027

Directions of Major Activities Related to Key Initiatives of Long-Term Vision LSV 2030

1 Resolve social issues

By March 2027, reduce CO_2 emissions by 67% or more compared with the fiscal year ended March 31, 2014
See pages 52–55.
Results for the fiscal year ended March 31, 2026 60.6% reduction

In addition to further expanding the range of environmentally friendly products and pursuing solventless products, work with related companies and the Japan-Earth Conscious Labeling (J-ECOL) to achieve the horizontal recycling of used release paper
See pages 52–55.
Results for the fiscal year ended March 31, 2026
Number of environmentally friendly products developed: 89
Percentage of solventless adhesive products for seals and labels: 80%

Curtail atmospheric emissions of volatile organic compounds (VOCs)
See pages 52–55.

2 Foster innovation to build a robust corporate structure

Implement portfolio restructuring, including withdrawal from unprofitable fields, after assessing the future growth potential, market competitiveness, and profitability of each business, and promote the sound management of domestic and overseas Group companies
See pages 18–21 and pages 22–23.

Introduce new production equipment to save energy, raise quality, increase efficiency, and reduce manpower, while at the same time enhancing cost competitiveness through production process innovation
See page 45.

Create value that exceeds the expectations of all stakeholders by putting specific action plans for LDX 2030 into action and accelerating the development of a transformational management foundation and corporate culture
See page 49.
Results for the fiscal year ended March 31, 2026
Transition to stage five of the plan, the execution stage

3 Create new products and businesses to deliver sustainable growth

Create a system for the early mass production of carbon nanotube (CNT) pellicles for extreme ultraviolet (EUV) lithography equipment, which were developed from elemental technologies
See pages 24–27 and page 32.
Results for the fiscal year ended March 31, 2026
Independent development of Dual Density carbon nanotube (CNT) pellicles that enhance durability and establishment of mass production technology

Utilize the newly established Package and Material Development Group to promote the development of new tapes, equipment, and proprietary processes related to packaging technology in advanced semiconductor back-end processes
See pages 24–29 and page 32.

Increase the ratio of overseas sales to total sales to 65% by the fiscal year ending March 31, 2027, by expanding and broadening the product lineup of adhesive paper and film, etc., to meet local needs in overseas markets
See pages 22–29 and pages 30–35.
Results for the fiscal year ended March 31, 2026 Overseas sales ratio: 62.8%

Material Issues

When formulating its medium-term business plan, LSV 2030–Stage 2, the LINTEC Group also revised its material issues and associated KPIs, taking into account changes in the external environment. Through the five newly defined material issues and our corresponding initiatives, we aim to contribute to the realization of a sustainable society.

Material Issues	KPIs	Targets
Work to solve social issues through business activities • Help shape a carbon-free world • Respect human rights of all stakeholders • Enhance governance and risk management ▶ **Pages 52–63**	Reduction in CO_2 emissions relative to fiscal year ended March 31, 2014 levels (reduction of 67% or more by March 2027, 75% or more by March 2030, and achievement of carbon neutrality by 2050)	*1
	Scope 1, 2, and 3 emissions	*1
	Non-fossil energy ratio	*3
	Implementation of CSR study sessions for such purposes as raising employee awareness and understanding of the Human Rights Policy	*1
	Number of themes adopted by the Corporate Risk Management Committee for deliberation	*1
	Total hours of discussion at high-level meetings (meetings of the Business Deliberation Council, Nomination and Compensation Committee, and Sustainability Committee)	*4
Foster innovation to build a robust corporate structure and promote sustainable growth • Create market-leading innovative new products and businesses • Reform development, manufacturing, transportation, operations, and other processes to improve profitability • Protect and utilize intellectual property ▶ **Pages 42–45 and Pages 48–49**	Target percentage of new product sales to total sales (27% by March 2027) (30% or more by March 2030)	*2
	Number of products developed	*2
	Number of development projects with external institutions	*4
	Number of LDX 2030 transformation themes implemented out of seven	*4
	Number of patent applications/patents held	*4
Fulfill responsibilities associated with the environment, society, and customers • Reduce impact on natural ecosystems • Increase development of environmentally friendly products • Provide and stably supply safe and high-quality products ▶ **Pages 52–57**	Increase in the use of solvent-free release agents and adhesive agents 1. Percentage of solvent-free release agents and adhesive agents used: 75% by 2030 2. Complete shift to solvent-free release paper by 2030 (all release paper produced at Kumagaya and Mishima plants, except specialty products)	*4
	Percentage of forest-certified paper and pulp used	*4
	Landfill disposal rate: 1% or less	*4
	Implementation of our release paper recycling system	*4
	Number of environmentally friendly products developed	*4
	Percentage of quality incidents	*5
Develop and secure human resources for the future • Respect human rights in general and the rights of employees • Improve human capital and create an honest and open organizational culture • Promote occupational health and safety ▶ **Pages 46–47 and Page 56**	Percentage of female managers/supervisors (Subsection Manager/Assistant Project Manager): 10%	*4
	Percentage of female among the total number of new hires (graduates from a junior college/university/graduate school): 35% or more	*4
	Percentage of persons with disabilities in the total number of employees: 2.7%	*4
	Number of participants in correspondence training programs	*4
	Occupational accident frequency rate	*6
	Occupational accident severity rate	*6
	Number of plants having no accidents in a year	*4
	Number of violations of occupational health and safety laws and regulations	*4
Maintain LINTEC's favorable reputation • Ensure transparent information disclosure and reinforce stakeholder communication • Ensure compliance and fair business practices • Promote responsible procurement and strengthen supply chains • Enhance information security ▶ **Pages 56–58**	Number of individual meetings held with institutional investors and analysts	*4
	Number of briefings held to explain financial results and for investor relations and total number of participants	*4
	Number of legal training programs provided and total number of participants (including archive viewers)	*4
	Periodic publication of Legal News (6 times a year) and total number of views (including number of emails sent)	*4
	Number of responses to CSR survey	*4
	Response rate of raw material supplier survey	*7
	Implementation of self-checks once a year based on the Information Security Operational Rules and Internal Audit Checklist	*4
	Implementation of e-learning information security self-audit once a year	*4

*1 LINTEC Group: LINTEC Corporation and consolidated and non-consolidated subsidiaries
*2 LINTEC Corporation and consolidated companies *3 LINTEC Corporation and domestic consolidated and non-consolidated subsidiaries *4 LINTEC Corporation
*5 LINTEC Corporation (excluding Ina Technology Center), TOKYO LINTEC KAKO, INC., and SHONAN LINTEC KAKO, INC. *6 LINTEC Corporation production plants and R&D facilities, TOKYO LINTEC KAKO, INC., and SHONAN LINTEC KAKO, INC.
*7 Suppliers providing raw materials to LINTEC Corporation
Note: Figures marked with ★ have been independently verified by SGS Japan Inc.

For more information on the process of formulating material issues, please refer to the sustainability section of our website.
www.lintec-global.com/sustainability/materiality/

Results for the Fiscal Year Ended March 31, 2025	Results for the Fiscal Year Ended March 31, 2026
52.5% (Scope 1 + Scope 2)	60.6% (Scope 1 + Scope 2)
Scope 1: 92,143 t-CO_2 / Scope 2: 66,925 t-CO_2 J-Credits: –18,762 t-CO_2 ★ Green Heat Certificates: –127 t-CO_2 ★ / Scope 3: 1,859,282 t-CO_2	Scope 1: 90,859 t-CO_2 / Scope 2: 54,232 t-CO_2 J-Credits: –28,922 t-CO_2 ★ / Scope 3: 1,801,452 t-CO_2
32.9%	41.5%
Prepared and disseminated a comparative version of the revised Code of Conduct Guidelines (updated in April 2024)	CSR-related training for new hires, new managers and new supervisors Launch of the employee sustainability information-sharing site Training and exchange meeting with LINTEC ADVANCED TECHNOLOGIES (TAIWAN)
Identified 18 themes related to regulatory risk	Identification of four corporate risks and enhancement of the governance system to address them
Board Directors meetings: 2 times (130 minutes) Nomination and Compensation Committee meetings: 4 times (295 minutes) Sustainability Committee meetings: 4 times (420 minutes)	Board Directors meetings: 0 times (0 minutes) Nomination and Compensation Committee meetings: 5 times (245 minutes) Sustainability Committee meetings: 4 times (440 minutes)
27.7% ★	24.9% ★
3,441	3,165
26	30
All 16 planned themes executed (to continue in the fiscal year ending March 31, 2026)	11 themes Consolidation of the originally planned 16 themes into 11, and implementing all of these (will be continued in the fiscal ending March 31, 2027)
Number of patent applications: 283 (fiscal year ended March 31, 2025) Number of patents held: 2,684 (as of March 31, 2025)	Number of patent applications: 237 (fiscal year ended March 31, 2026) Number of patents held: 2,720 (as of March 31, 2026)
Release agents: 71% Adhesive agents: 80%	Release agents: 73% Adhesive agents: 80%
Forest-certified paper: Certified material ratio (purchased): 29.4% Forest-certified pulp: Certified material ratio (purchased): 55.9%	Percentage of forest-certified paper used (purchased): 30.5% Percentage of forest-certified pulp used (purchased): 52.4%
0.26%	0.24%
We conducted educational outreach on the recycling of release liners through activities with the Japan-Earth Conscious Labeling (J-ECOL). We also promoted circular economy initiatives through collection systems, re-commercialization systems, and reuse schemes.	Through the activities of J-ECOL (Japan-Earth Conscious Labeling), conducting activities aimed at the practical implementation of recycling of release liners • Total collected release liners: 536t (approx. 7.6 million m² (calculated at 70g/m²)) • Publication of case studies (on J-ECOL website) • Traceability demonstration experiment • Establishment of technologies for horizontal recycling, and market evaluation
73	89
31% (compared for the fiscal year ended March 31, 2011 levels)	29% (compared for the fiscal year ended March 31, 2011 levels)
7.7% ★	8.6% ★
43.9% ★	39.7% ★ (regular hires as of April 1, 2025)
2.53% ★	2.54% ★
283	310
0.18 ★	0.72 ★
0.0143 ★	0.0366 ★
3 site (Chiba Plant, Kumagaya Plant, and the Research & Development Division)	4 site (Kumagaya Plant, Agatsuma Plant, Mishima Plant, and Ina Technology Center)
0	1
311 companies (total)	284 companies (total)
3 times, 317 employees (total)	3 times, 359 employees (total)
6 times, 471 employees (on-site and online participants)	6 times, 1,383 employees (on-site and online participants)
6 times, 2,828 times	6 times, 2,444 times
224 (Number of cases investigated by the Sustainability Management Office in response to the survey)	163 (Number of cases investigated by the Sustainability Management Office in response to the survey)
Activities implemented after the supplier questionnaire in the fiscal year ended March 31, 2024 1. Number of feedback sessions conducted (number of suppliers who received feed- back in the year ended March 31, 2025): 48 companies, 62 business units ★ 2. Number of suppliers who received improvement requests (in the year ended March 31, 2025): 5 companies, 5 business units ★	Activities implemented after the supplier survey conducted in the fiscal ended March 31, 2024 • Percentage of suppliers who received a second response to improvement requests 80.0% ★
Information security training regarding connections required for external users to access internal system Implementation period: December 2–22, 2024	Implement information security training regarding connections required for external users to access internal systems Implementation Period: October 6–31, 2025 (General security education) December 2–19, 2025 (Training on the explanation and application process for internal corporate network connection access rights)
Implemented two times 1st time: July 1–October 31, 2024 2nd time: January 20–March 22, 2025	Implemented three times Implementation period (1st time): June 2–July 31, 2025 Implementation period (2nd time): September 16–November 30, 2025 Implementation period (3rd time): March 2–31, 2026

Financial Strategy A Message from the CFO

Financial Capital



1. Review of the Fiscal Year Ended March 31, 2026, and Outlook for the Fiscal Year Ending March 31, 2027

In the fiscal year under review (fiscal year ended March 31, 2026), we saw further record highs for net sales, operating income, and profit attributable to owners of parent. I believe that our ability to achieve such positive results in a highly uncertain business environment, which includes the significant disruption to various economies around the world brought about by U.S. tariff policy, is evidence of the steady improvement of our profitability. The driver of our performance has been Advanced Materials Operations, which develops semiconductor- and electronic component-related products. We recorded high levels of sales of the mainstay products in this business segment—semiconductor-related adhesive tape and equipment and multilayer ceramic capacitor-related tape—by solidly capturing the rise in demand related to AI. Despite a slight year-on-year decrease in sales of semiconductor-related equipment, there are signs of improvement, as we are seeing a steady recovery in both orders and deliveries for tools for high-bandwidth memory (HBM) manufacturing. This business segment is expected to maintain its strong performance in the current fiscal year (fiscal year ending March 31, 2027). Against a backdrop that includes the current status of the semiconductor market and strong capital investment by customers, all mainstay products are on track to achieve record-high sales.

For the fiscal year ending March 31, 2027, we forecast higher net sales and income. We anticipate operating income

Consolidated Operating Performance

	Fiscal Year Ended March 31, 2024	Fiscal Year Ended March 31, 2025	Fiscal Year Ended March 31, 2026	Forecast for the Fiscal Year Ending March 31, 2027
Net Sales	¥276,321 million	¥315,978 million	**¥319,385 million**	¥342,000 million
Operating Income [Operating Profit Margin]	¥10,628 million [3.8%]	¥24,562 million [7.8%]	**¥25,156 million [7.9%]**	¥27,500 million [—]
Profit Attributable to Owners of Parent	¥5,243 million	¥14,476 million	**¥17,374 million**	¥19,500 million
Return on Equity (ROE)	2.3%	6.1%	**6.9%**	—
Return on Invested Capital (ROIC)	3.1%	6.9%	**6.7%**	—
Weighted Average Cost of Capital (WACC)*	5.3%	6.0%	**6.1%**	—
Price-to-Book Value Ratio (PBR)	0.93 times	0.76 times	**1.14 times**	—

* LINTEC uses the capital asset pricing model to calculate WACC.

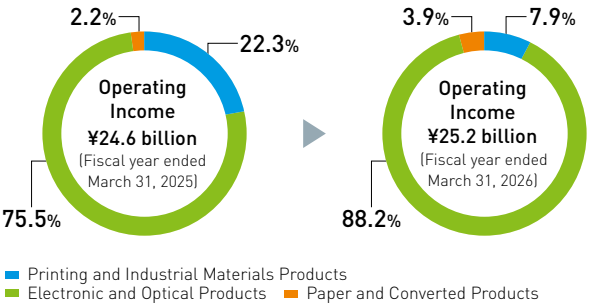
to increase 9.3% year on year, to ¥27.5 billion. While we anticipate higher sales volumes to contribute ¥4.8 billion and price revisions to contribute ¥5.3 billion, rises in raw material prices will reduce income by ¥4.7 billion, and increases in fixed costs, such as labor and research and development expenses, will reduce income by ¥4.2 billion. Furthermore, in breaking down raw material prices, we must account for the impact of escalating tensions in the Middle East, which we estimate to be ¥3.0 billion. In fact, while raw material prices began to significantly rise in May 2026, our Procurement Division strove to secure raw materials before these price hikes, and we are making every effort to ensure a stable supply of products. In response to the impact of Middle East tensions, we implemented price revisions in Printing & Variable Information Products Operations on shipments from July 1, 2026. We also considered and are currently implementing price revisions in other business segments. Since these price revisions are not incorporated into our performance forecasts, we believe they will serve as a positive factor for our performance.

2. Improving MACTAC AMERICAS' Profitability—A Key Challenge

Our strong financial performance clearly reveals a profit structure issue, as approximately 90% of our operating income comes from electronic and optical products, including Advanced Materials Operations, and the source of our income is heavily concentrated in a specific business division. In the fiscal year under review, operating income for Printing and Industrial Materials Products fell 63.8%, to ¥2.0 billion. However, the main factor behind this decline was the recording of an approximately ¥3.9 billion operating loss for MACTAC AMERICAS, LLC, our American subsidiary. In light of this situation, we must put considerable effort into driving improvements to profitability. As for the decline in process yield, the cause of the worsening operating loss, we have dispatched a team from Japan that includes engineers to address the issue. We anticipate seeing the effects of our improvements from around the second quarter of the current fiscal year. In addition, we implemented price revisions in April 2026 to cover soaring raw material costs, which are expected to result in several billion yen.

MACTAC AMERICAS will cease amortization of goodwill in November 2026. Since the burden of nearly ¥4.0 billion will be eliminated in the next fiscal year, we expect to remain in the black. However, as a business, we will aim to remain profitable. We aim to return to an operating profit margin of 10% as soon as possible, which was the rate we achieved prior to acquisition. Accordingly, we will expand our product lineup from the adhesive papers that have conventionally been our mainstay product to include adhesive films, which provide even more added value, as we strive to improve both unit price and profit margin. We will also implement measures to improve profitability while exploring ways to optimize our production and logistics sites.

Operating Income Breakdown by Segment



Note: The composition ratio is based on figures before elimination of transactions between segments.

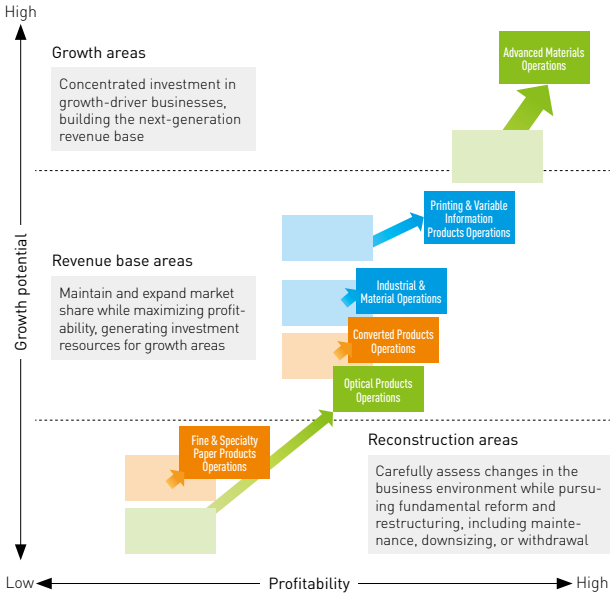
3. Achievement of Crucial Targets Under Our Long-Term Vision

We estimate that our weighted average cost of capital (WACC) for the previous fiscal year was 6.1%. To consistently achieve a price-to-book value ratio (PBR) above 1.0, we recognize the importance of consistently maintaining a return on equity (ROE) that exceeds WACC. We have adopted an operating profit margin of 12% or more and ROE of 10% or more as a financial target for the final year of our medium-term business plan, LSV 2030–Stage 3 (fiscal year ending March 31, 2030). LINTEC's businesses are divided into three categories—growth areas, revenue base areas, and reconstruction areas. The key to achieving the above indicators is raising the profitability of our entire business portfolio. In addition to the aforementioned MACTAC AMERICAS, we also need to improve profitability in the reconstruction areas of Optical Products Operations and Fine & Specialty Paper Products Operations. Under the ongoing Stage 2 of the medium-term business plan, we closed two consolidated subsidiaries in South Korea and Taiwan that had been engaged in adhesive processing for polarizing films under Optical Products Operations. We have also seen a harsh external environment for Fine & Specialty Paper Products Operations with a shift from paper to digital media, which has lowered the sales volume for our core product, color papers for envelopes. Although not reflected in our financial results, Fine & Specialty Paper Products Operations plays a vital role in producing base paper for release paper and

selling it internally to Converted Products Operations. This supports our integrated production system for adhesive products that is a LINTEC strength. With that said, improving profitability is still essential. In addition to recording impairment losses on fixed assets of ¥7.7 billion for the fiscal year ended March 31, 2025, we are implementing fundamental structural reforms, such as shutting down one of the paper machines operating at the Kumagaya Plant (Saitama Prefecture) to save on fixed costs.

In recent years, we have received numerous questions regarding optimization of our business portfolio at IR meetings, but we have not set uniform rules for investments and withdrawals. This is because we believe that, in a rapidly changing business environment, the ability to accurately assess each situation and make timely decisions allows for flexible responses aligned with individual circumstances. Accordingly, I view it as my important role to communicate clearly and sincerely with shareholders and investors, explaining the background behind our initiatives as well as LINTEC's thinking and unique strengths.

Current Status of Each Business Operation and Direction Going Forward

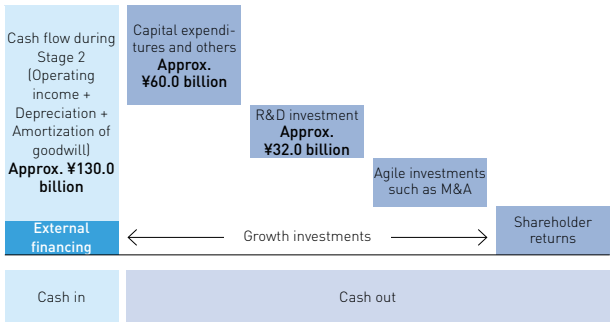


4. Cash Allocation to Support Sustainable Growth

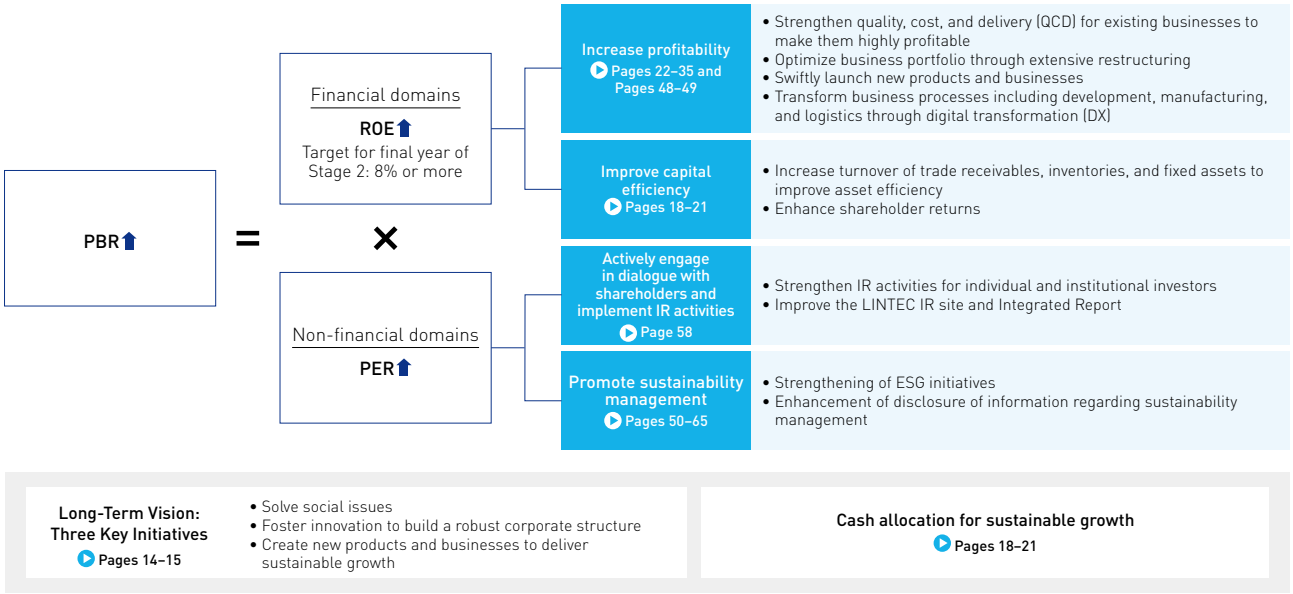
While we are advancing structural reforms in business operations that require improvements in profitability, we will enhance our competitive edge in Advanced Materials Operations, which is a growth area, by actively investing funds in R&D and capital expenditures. In the fiscal year under review, we actively pursued growth investments in our semiconductor-related businesses, investing a total of ¥3.0 billion in establishing a mass production system for carbon nanotube (CNT) pellicles for extreme ultraviolet (EUV) lithography equipment, expanding and renovating the Ina Technology Center (Saitama Prefecture) to strengthen supply capacity for semiconductor-related equipment, and constructing new research facilities for developing new products such as semiconductor-related adhesive tape. In the current fiscal year, we will continue projects carried over from the previous period, as well as advance new initiatives such as building new systems related to advanced semiconductor manufacturing processes. Regarding our forecast of only a 2.6% year-on-year increase in operating income for electronic and optical products for the current fiscal year, we have received numerous questions from investors asking whether this forecast is overly conservative relative to the growth of the global semiconductor market. This forecast reflects increased fixed costs and rising raw material prices due to escalating tensions in the Middle East. However, given that actual results in the fiscal year under review significantly exceeded initial forecasts, I believe there is considerable potential for performance to exceed the current projection. Proactive investment in growth areas such as Advanced Materials Operations is central to our Companywide strategy. Currently, our Companywide R&D expenditure to sales ratio is approximately 4%, and we are considering raising this to around 10% in the future. We will disclose our cash allocation plans for the next medium-term business plan period at an appropriate time.

In addition, as part of our efforts to refine management, we will continue managing our businesses using return on invested capital (ROIC). Asset turnover rates are trending favorably, reflecting steady progress toward management practices that emphasize capital efficiency. In the current fiscal year, we have established KPIs such as inventory turnover, trade receivables turnover, and fixed asset turnover, promoting improvement activities across each business operation. We also introduced a new ROIC management accounting system in April 2026. We have strengthened our framework by inputting quarterly performance data for each business operation, enabling data-driven progress management and decision-making. We believe this will further advance improvements in profitability and capital efficiency across each business operation.

Cash Allocation Under LSV 2030–Stage 2



Initiatives to Achieve Management Mindful of Cost of Capital and Stock Price

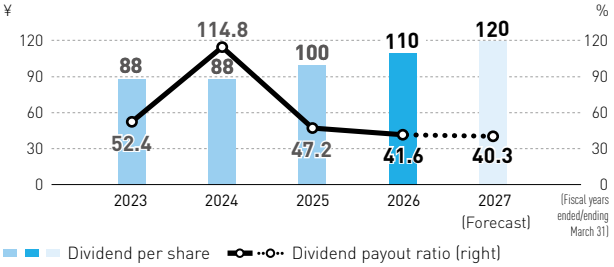


5. Constructive Dialogue with Shareholders and Investors

During IR meetings with investors, we receive questions regarding the optimization of our business portfolio. We also receive requests for strengthening shareholder returns, such as the aforementioned clarification of cash allocation, promotion of ROIC management, and ongoing share buybacks and dividend increases. Regarding share buybacks, we repurchased 3 million shares (approximately ¥8.3 billion) in June 2025. Going forward, we will continue to implement flexible share buybacks as appropriate, taking into account cash on hand and assessing the necessity of such actions. Our basic policy through the fiscal year ending March 31, 2027 is to avoid dividend reductions, in principle, and maintain a dividend payout ratio of 40% or higher or a dividend on equity (DOE) ratio of 3% as a benchmark. For the current fiscal year, we plan to increase the dividend by an additional ¥10, to ¥120, marking the third consecutive year of dividend increases.

Despite a significant fall in our stock price due to the shock caused by President Trump's tariffs in April 2025, we have since seen a strong resurgence in performance and our stock price has consistently maintained a PBR above 1. I believe this reflects strong market interest in our competitive semiconductor-related businesses, as well as positive recognition from investors for our ability to swiftly implement structural reforms in response to their expectations. At present, we continue our dialogue with the market through ongoing communication with institutional investors both in Japan and overseas, as well as continued participation in corporate presentations for individual investors. We will continue to strive for further improved corporate value and acquisition of market recognition through active information disclosure and constructive dialogue.

Dividend per Share / Dividend Payout Ratio





Special Feature 1

Key Measures Aimed at Business Transformation and Growth Acceleration

Transformation to a Profit-Oriented Structure

Looking back at our business transformation, Healthcare Products Operations, which had handled medical adhesive products, was integrated into Printing & Variable Information Products Operations in 2011. Subsequently, we exited the solar panel backsheet business in 2017 as part of efforts to streamline operations at our U.S. subsidiary. In the same manner as the dissolution and liquidation of a Chinese subsidiary that had been involved in the manufacture and sale of label printing machines in 2018, we have made management decisions, when necessary, from a profitability viewpoint of selecting and aggregating our businesses. Under our medium-term business plan, LSV 2030–Stage 2, we are also optimizing our business portfolio through fundamental structural reforms while simultaneously strengthening growth areas and improving profitability at low-profit businesses. This special feature introduces initiatives aimed at transforming our business segments and consolidated subsidiaries to profit-oriented structures, which are topics on which we have received numerous inquiries from our stakeholders.

MACTAC AMERICAS, LLC

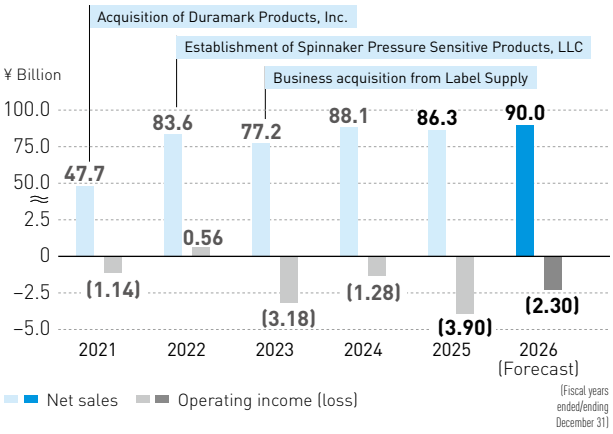
MACTAC AMERICAS is a manufacturer with the No. 3 share of the North American market, which comprises approximately 20% of the global market for adhesive papers and films for labels. We acquired the company in December 2016 for approximately ¥34.0 billion with the aim of making a full-scale entry into the North American market. Its strength is a hot-melt adhesive, which is solid at room temperature and applied in molten form. Because it is solventless, it has a minimal environmental impact and eliminates the need for drying processes, which also reduces CO_2 emissions during manufacturing. MACTAC AMERICAS demonstrates technology-based synergies, such as introducing products that utilize these adhesive formulations into the Japanese market, through the Printing & Variable Information Products Operations, which is a core business of the Group. Meanwhile, looking at financial performance, the Group continues to face profit margin pressures, largely due to goodwill amortization costs of approximately ¥30.0 billion incurred from the acquisition. The fiscal year ended December 31, 2025 saw operating losses of approximately ¥3.9 billion, the largest since the acquisition, against a backdrop of persistently high raw material prices, worsening market conditions in North America, declining process yield, and other factors.

In the fiscal year ending December 31, 2026, we anticipate operating losses of ¥2.3 billion, shrinking the deficit by approximately ¥1.6 billion year on year. Regarding the declining process yield, the largest factor behind the widening operating loss in the previous fiscal period, we have dispatched a team from Japan, including engineers, to implement countermeasures. We have also strengthened communication with the management and manufacturing departments at MACTAC AMERICAS to accurately assess progress in addressing these business challenges. In response to the impact of the situation in the Middle East, we implemented price revisions for adhesive paper and film for printing in April 2026. We estimate that these price revisions will generate several billion yen in revenue and expect them to offset the decline in sales volume caused by the cooling of the North American market. In terms of yen, this amortization has exceeded ¥4.0 billion for the three consecutive years beginning in the fiscal year ended December 31, 2023, due to the currency's depreciation. Although the amortization of goodwill will end in November 2026, we are working to improve our product mix, such as by expanding our product lineup of adhesive films for high-value-added industrial applications, while also continuing to review our supply chain and optimize our production and logistics facilities, with the aim of transforming our business into a profit-oriented structure.



Adhesive products for labels using hot-melt-type adhesives

MACTAC Group's Performance



Optical Products Operations

In the fiscal year ended March 31, 2025, we closed two overseas production subsidiaries in South Korea and Taiwan that had been engaged in adhesive processing for polarizing films, leaving the business operated solely by LINTEC Corporation. Although the scale of the business has decreased, profitability is expected to improve following the dissolution of these two companies, which had suffered from declining performance as orders fell sharply amid the growing presence of Chinese manufacturers in the LCD-related industry. Furthermore, in line with reorganization of businesses by existing partners, we shifted our business strategy by scaling down our LCD-related business to focus on higher-performance areas such as organic electroluminescence (EL) displays. For the Opteria series, which we believe will be key to improving earnings, we are pursuing sales expansion through proprietary products such as onboard optical clear adhesive sheets, light-diffusing film, and high-barrier film. We have also implemented price revisions to pass on cost increases associated with heightened tensions in the Middle East. Through continued structural reforms, we aim to transform this business into a profit-generating foundation capable of creating resources for investment in growth areas.

Fine & Specialty Paper Products Operations

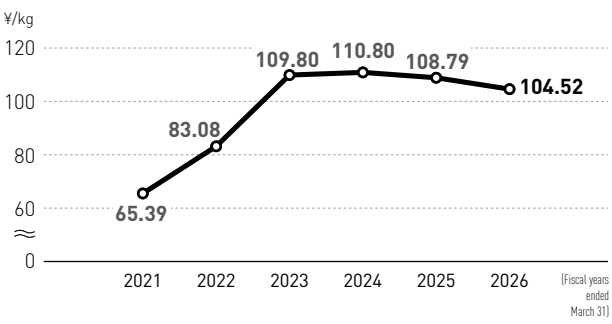
By producing base paper for release paper and supplying it internally to the Converted Products Operations, the business fulfills an important role that is not fully reflected in its financial performance and supports LINTEC's integrated production system for adhesive products, one of our core strengths. Meanwhile, orders have remained sluggish in recent years, particularly for our core product, color papers for envelopes, due to the growing shift from paper to digital media and paperless operations, as well as postage rate hikes. Following a review of the future recoverability of Fine & Specialty Paper Products Operations in the fiscal year ended March 31, 2025, we recorded impairment losses of approximately ¥7.7 billion on fixed assets. We are also promoting structural reforms, including the shutting down of one of the paper machines at the Kumagaya Plant (Saitama Prefecture) by the end of March 2026, which is expected to reduce fixed costs by several hundred million yen. On the product front, as demand grows for reducing and eliminating plastic use amid rising environmental awareness, we see opportunities in special function paper, developed using LINTEC's proprietary papermaking technology, and are working to expand sales. One example is oil-resistant paper used in food packaging, such as wrappers for french fries and similar products. With increasing efforts to regulate the use of perfluoroalkyl and polyfluoroalkyl substances (PFASs), particularly in the United States and Europe, we are aiming for a complete transition to oil-resistant papers that do not use fluoropolymer coatings, which is seeing increasing adoption by convenience stores, fast-food chains, and other customers. We are also advancing the development of high-performance papers as plastic alternatives, including transparent papers and biodegradable heat-sealing papers.

In response to rising raw material, fuel, and logistics costs, we implemented price revisions for specialty papers effective February 2026. As profits in this business are significantly affected by pulp raw prices, we are also implementing procurement initiatives, including increasing the use of lower-cost domestic pulp to mitigate the impact of exchange rate fluctuations on imported materials. For the fiscal year ending March 31, 2027, net sales are expected to remain at approximately the same level as in the previous fiscal year, while profits are expected to improve.



Example of oil-resistant paper in use

Pulp Prices



Special Feature 2

Key Measures Aimed at Business Transformation and Growth Acceleration

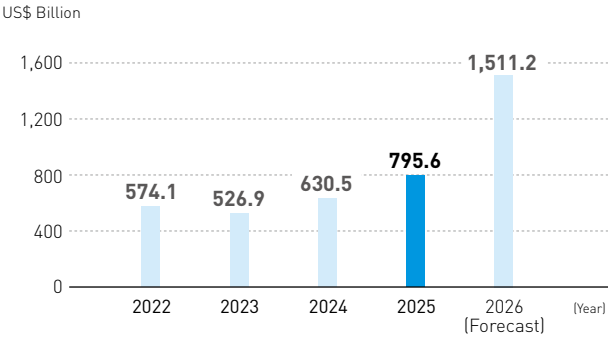
Expansion of the Semiconductor-Related Business

Advanced Materials Operations, which develops and markets semiconductor-related products, is driving the Company's growth. Operating income in the Electronic and Optical Products segment, which includes Advanced Materials Operations, increased 19.5% year on year, to ¥22.1 billion, in the fiscal year ended March 31, 2026, serving as a key driver behind record-high consolidated operating income. The global semiconductor market is expected to continue expanding, supported by growing demand for high-performance semiconductors used in data centers and other applications. We are actively investing in R&D and other initiatives in the semiconductor-related business, which we have positioned as a growth area, to further strengthen our competitiveness over the long term. This special feature outlines our initiatives for achieving sustainable growth.

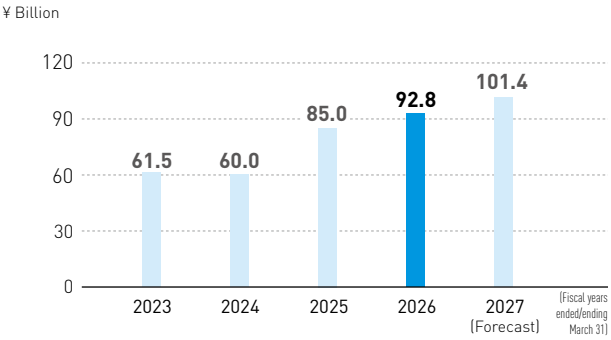
A Rapidly Expanding Semiconductor Market

In recent years, the global semiconductor market has expanded rapidly, driven by growing demand related to AI. In June 2026, the World Semiconductor Trade Statistics (WSTS) organization forecast that the global semiconductor market would expand 89.9% year on year, to US$1.5 trillion in 2026. This represents an upward revision of more than US$530 billion in just six months from the forecast released in December 2025, making it increasingly likely that the market will surpass the US$1 trillion mark. Continued aggressive investment in data centers by major IT companies is expected to support growth, with memory chips and logic products, including GPUs, for AI servers anticipated to lead market expansion. Advanced Materials Operations has also successfully captured growth in the semiconductor market, with net sales reaching a record high of ¥92.8 billion in the fiscal year ended March 31, 2026. The business accounts for approximately 30% of consolidated net sales, and net sales are projected to increase 9.3% year on year, to ¥101.4 billion in the fiscal year ending March 31, 2027.

Forecast for Global Semiconductor Market



Net Sales in Advanced Materials Operations



Source: World Semiconductor Trade Statistics (WSTS)

LINTEC Products Utilized in the Manufacturing and Implementation Processes of Semiconductor Chips

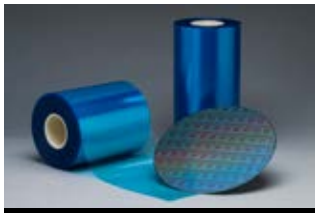
The core products of Advanced Materials Operations are semiconductor-related adhesive tapes and equipment and multilayer ceramic capacitor-related tapes. As an overview of the sales composition, semiconductor-related adhesive tapes comprise approximately 50% of the business and equipment comprises approximately 20%–30%, with the remainder of net sales attributed to multilayer ceramic capacitor-related tapes. Semiconductor-related adhesive tapes, which make up around half of the net sales of Advanced Materials Operations, incorporate LINTEC's cutting-edge technology and are utilized in the manufacturing and implementation processes of semiconductor chips. Over many years, we have seen a correlation between the sales volume for semiconductor-related adhesive tapes and the global shipping area for semiconductor wafers. However, while the global shipping area for semiconductor wafers remains limited to an approximately 5% increase compared with five years ago, net sales for semiconductor-related adhesive tapes have greatly exceeded the growth rate for shipping area in recent years, in fact, recording a roughly 60% increase. We believe this growth was driven by increased demand for our products for high-end

applications, supported by continued strong demand for high-bandwidth memory (HBM), which is produced by stacking DRAM semiconductor memory chips, as well as robust sales of new high-performance smartphone models. At the Agatsuma Plant (Gunma Prefecture), the core production site for these tapes, we had completed approximately ¥4.5 billion in capacity expansion investments by the fiscal year ended March 31, 2025 in anticipation of growing semiconductor demand, establishing a production system capable of meeting robust market demand.

Net Sales for Semiconductor-Related Adhesive Tape

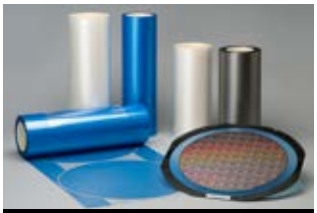
60% increase over **five** years

Adwill Series Semiconductor-Related Tapes



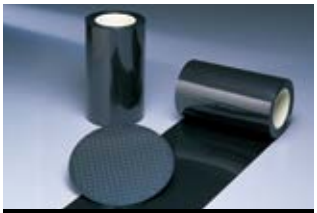
Back grinding tape

This type of tape protects the wafer surface during the back grinding process (which involves thinning the backside of the wafer by grinding), preventing contamination of the circuit surface by grinding water or debris.



Dicing tape

Dicing tape firmly holds individual chips in place during dicing, which then allows easy pickup after UV irradiation reduces adhesive strength.



Backside coating tape

This tape is used in applications such as flip chip mounting, where chips are installed face down on the substrate. This tape protects and reinforces the backside of the chip.



Dicing die bonding tape

Like conventional dicing tape, dicing die bonding tape firmly secures the wafer during dicing. However, when the chips are picked up, an adhesive material is transferred to the chips' backside for bonding purposes.

Strengthening Production Capabilities for Semiconductor-Related Equipment

We are able to provide comprehensive proposals for both software (materials) and hardware (equipment) by developing and producing related equipment that fully demonstrates the characteristics of our adhesive products. Semiconductor-related equipment includes wafer mounters, tape laminators, tape removers, and UV curing systems. Equipment for HBM manufacturing, which applies tape used in the process of stacking DRAM, began receiving orders and shipments from the second half of the fiscal year ended March 31, 2024, recording sales of approximately ¥9.0 billion in the fiscal year ended March 31, 2025. We have secured a high level of orders for semiconductor-related equipment, including HBM manufacturing equipment, and anticipate overall equipment sales for the fiscal year ending March 31, 2027 to grow by more than double digits year on year. As with semiconductor-related adhesive tape, demand is expected to continue expanding, and we are therefore enhancing the production capacity of the Ina Technology Center (Saitama Prefecture), which handles everything from the design and development to the production of various equipment. Specifically, by renovating part of the existing building while also constructing a new building, we will expand the production space for semiconductor-related equipment to approximately 1.6 times its current size. Operations are scheduled to begin in October 2026, enabling us to respond to needs for increased production volumes and shorter delivery times.



Production Space

Approx. **1.6** times

Forecast for Sales Changes of Advanced Materials Operations' Three Core Products (Comparison with the Fiscal Year Ended March 31, 2026)

UP
DOWN

UP Semiconductor-related equipment

Orders for HBM manufacturing equipment expected to grow due to recovery from the previous half

UP Multilayer ceramic capacitor-related tape

Increase in demand anticipated, driven by smartphones, AI servers, use in automobiles, and other factors

UP Semiconductor-related adhesive tape

Continued increase in sales volume anticipated due to strong demand, driven by AI

Expansion of the Semiconductor-Related Business

To date, technological innovation in the semiconductor industry has continued in line with Moore's Law, which denotes that the integration density of semiconductor circuits doubles every two years. As semiconductors reach their physical limit for miniaturization, we are focusing on the keys to further advancing semiconductors, such as packaging technology that enables high-density mounting of multiple chips in a single package. We are advancing business activities that recognize the de facto standard for the world in five to six years' time and are proactively engaging in strengthening our R&D system in the advanced semiconductor field and expanding into new fields.

Strengthening Development of New Materials and Process Technologies for Advanced Semiconductors

We have built a new Advanced Development Center as a research facility equipped with a clean environment in the Advanced Technology Building at our Research Center (Saitama Prefecture). In recent years, chiplet technology that combines numerous small chips through high-density mounting and stacking on one package has been progressing in the advanced semiconductor field, including HBM and logic semiconductors. As high-density and stacked chips advance, we are seeing increasing importance for technology that includes hybrid bonding that directly bonds chips without the need for adhesives. In direct bonding, minor contamination and residue significantly impact yield and reliability, and therefore, it is essential to appropriately manage and assess the materials and processes in manufacturing operations that involve chips. We have also equipped the center with ISO Class 5/Class 7 clean rooms. In addition to our own equipment, we will introduce externally manufactured middle- and back-end equipment and inspection systems to expand and reinforce our capabilities to conduct evaluations under conditions that closely resemble the mass production line. These evaluations cover materials and processes, including semiconductor-related adhesive tape, such as those used for HBM, for which low contamination and low residue are critical requirements.



Advanced Technology Building, Research Center

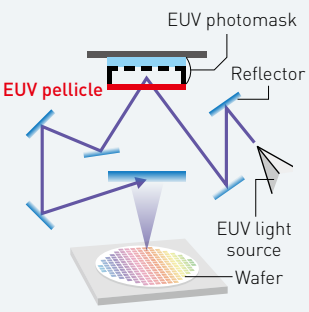
Accelerating Initiatives for Development and Full-Scale Production of CNT Pellicles

In June 2026, we opened LINTEC Tsukuba Innovative Creation Center within the Tsukuba Central site of the National Institute of Advanced Industrial Science and Technology (AIST) in Ibaraki Prefecture as a new R&D and production site. At this site, we have also introduced production equipment and related equipment for CNT pellicle film for EUV lithography equipment that is essential for advanced semiconductor microcircuit fabrication. First, we plan to launch a supply of full-sized pellicle samples, while conducting a phased introduction of ancillary equipment necessary for verification systems and product supply. Pellicles differ from the various high-performance tapes and related equipment used in the back-end processes of semiconductor manufacturing that LINTEC has developed to date, and are components used in the front-end processes of semiconductor manufacturing. Pellicles, which prevent contamination from adhering to photomasks (the master templates for circuit patterns), have traditionally been made from materials based on polysilicon and other conventional substrates. However, as the performance of EUV lithography systems (which are vital for forming the fine circuit patterns of advanced semiconductors) continues to improve, there is growing demand for CNT pellicles that offer superior durability and reliability. Based on customer evaluations of product samples, we will accelerate efforts toward further product development and full-scale commercial production.



Production equipment for newly introduced pellicle film

Inside an EUV lithography system



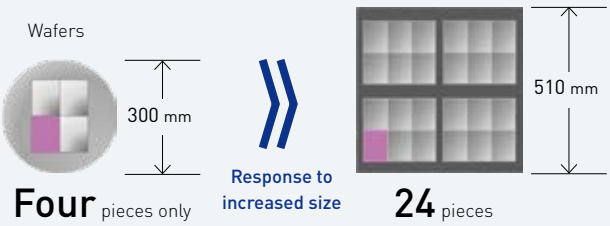
LINTEC's History with Pellicles

Year	Key Initiatives and Milestones
2018	**Launched development of pellicles at Nano-Science & Technology Center, an R&D site in Texas (U.S.)** Explored new applications for CNT (carbon nanotube) technology, which have been a research topic since 2013, at the same site
2023	**October: Commenced joint research with the National Institute of Advanced Industrial Science and Technology (AIST)'s Semiconductor Frontier Research Center (SFRC)**
	December: Announced establishment of elemental technologies for CNT pellicles for EUV lithography equipment Disclosed LINTEC's decision to invest approximately ¥5 billion to establish its first-phase mass production system
2024	**July: Successfully launched mass production system for CNT pellicles** Developed Group proprietary mass production system
	September: Announced that mass production was on track
2026	**February: Announced establishment of new coating formulation that realizes enhanced durability for CNT pellicles** Developed proprietary dual-density CNT pellicles that enhance durability and established mass production technologies For more details: www.lintec-global.com/topics/products/2026/260217_a.html
	May: Announced opening of LINTEC Tsukuba Innovative Creation Center
	June: Opened LINTEC Tsukuba Innovative Creation Center Launched supply of full-sized pellicle samples at the same time as phased introduction of incidental equipment necessary for inspection systems and product supply

Driving Continuous Innovation Through Enhanced Co-Creation Initiatives

In September 2025, we announced our participation in JOINT3, a consortium for next-generation semiconductor packaging established by Resonac Corporation. JOINT3 brings together world-leading companies in the fields of semiconductor materials, equipment, and design to advance the development of materials, manufacturing equipment, and design tools optimized for panel-level organic interposers. As semiconductor performance continues to improve, interposers are becoming larger, accelerating the shift from silicon interposers to organic interposers that utilize organic materials. The mainstream manufacturing method involves cutting square interposers from circular wafers. However, as the size of interposers increases, the number of interposers that can be produced from a single wafer decreases, creating a significant manufacturing challenge. To address this challenge, growing attention is being paid to manufacturing processes that replace circular wafers with square panel formats, thereby increasing production yield. We are also focused on establishing technologies for next-generation semiconductor packaging, and participation in JOINT3 represents one part of this initiative. Building on the adhesive and equipment technologies we have cultivated over many years, we will collaborate with other participating companies to create new proprietary technologies. By integrating diverse technologies at a higher level, we aim to contribute to the further advancement of semiconductor packaging technologies. We will also continue to promote co-creation-based R&D with companies and external institutions at the Advanced Development Center. In addition to developing our own products, we will conduct material evaluations and process verification in collaboration with customers, thereby strengthening our ability to respond to the rapid evolution of leading-edge semiconductor technologies.

Increase in Number of Pieces Due to a Change in Panel Shape



Special Feature 3

Key Measures Aimed at Business Transformation and Growth Acceleration

Creation of New Growth Engines

We are seeing significant growth opportunities in the semiconductor market against a backdrop of AI popularization. Meanwhile, semiconductor manufacturing technology is currently in the midst of rapid advancement, meaning that we cannot guarantee our current competitive edge in the future. If we fall behind in our response to these advancements, we anticipate a significant impact on our ability to achieve sustainable growth. It is for this reason that taking the initiative with medium- to long-term changes is vital. The final section of this special feature will introduce initiatives aimed at the further enhancement of our competitive edge in the semiconductor-related business, so that we can continue being the most important and strongest supporter for our customers, as well as the creation of new products and businesses that will shape the future.

Strengthening of Our Capability to Adapt to Next-Generation Semiconductor Manufacturing Processes

A priority measure aimed at strengthening the semiconductor-related business from a medium- to long-term perspective is the investment of approximately ¥20.0 billion in the opening of the Semiconductor Solutions Lab, a new research facility. In 2023, we established the Package and Material Development Group within the Fukuoka Solution Center for Advanced Semiconductor Packaging (formerly the Research Center for the Three-Dimensional Semiconductors), operated by Fukuoka Industry, Science & Technology Foundation, to expand our lineup of semiconductor-related products and promote the development of new processes related to semiconductor manufacturing. At the Semiconductor Solutions Lab, which we plan to open on an adjacent site, we aim to further expand the development of tape, equipment, and processes related to packaging technology, while strengthening our technological foundation with an eye to medium- to long-term growth based on structural changes in the semiconductor industry. LINTEC concluded a location agreement with Fukuoka Prefecture and Itoshima City in August 2026 and aims to finish construction in October 2028.

The decision to establish the Lab was driven by both growing demand for semiconductors, including those used in AI applications, and the fact that semiconductor manufacturing technology is undergoing a major transformation. As semiconductor devices become increasingly high-performance and highly integrated, the distinction between front-end and back-end processes is becoming less clear. At the same time, technological innovations in middle processes, such as 3D packaging and chiplet stacking, are advancing, increasing their importance in terms of performance, yield, and reliability.

The Lab will feature clean rooms and will be equipped with middle-process and back-end-process equipment used in actual production lines, including both our own equipment and that of other manufacturers, as well as a wide range of analytical and evaluation instruments. Positioned as a co-creation and rapid-response development hub where we work closely with customers to advance technology development, the Lab aims to facilitate adaptation to next-generation manufacturing processes at an early stage. The Group operates Application Centers equipped with back-end-process equipment in Japan, Taiwan, Malaysia, and North America, providing services such as optimization proposals for tape lamination and debonding conditions, material evaluation, and process verification. Through close collaboration with these Application Centers, the Lab will strengthen our global R&D framework and enable the entire Group to enhance its comprehensive proposal capabilities across materials, equipment, and processes.

Semiconductor Solutions Lab

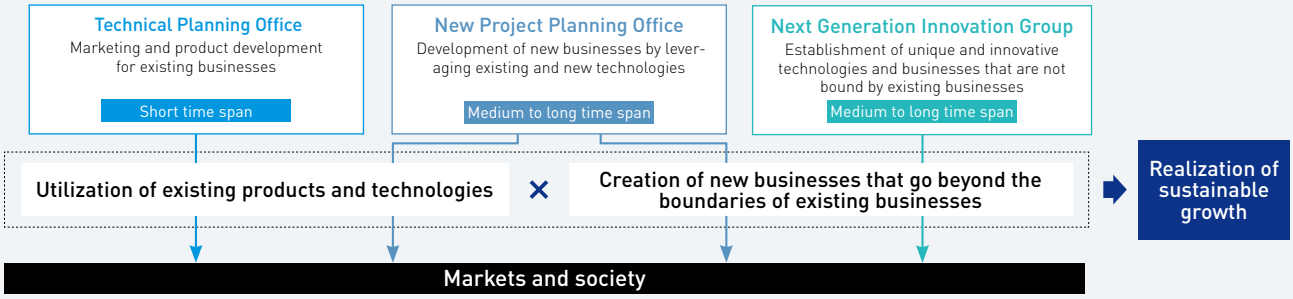
Summary

Investment amount	Approx. ¥20.0 billion
Planned completion of construction	October 2028
Location	Itoshima-shi Higashi, Fukuoka Prefecture
Site area	3,435 m²
Building	Three floors above ground with a total area of approx. 5,000 m²
Number of employees	Approx. 25 planned (15 at the time of opening)
Details of research	Materials for manufacturing semiconductors and electronic components, etc.

Initiatives We Want to Achieve

- Development of new materials, equipment, and processes as a co-creation and rapid-response development site for our customers
- Early adaptation to next-generation semiconductor manufacturing processes as a place for joint research with our customers
- Reinforced R&D on a global scale by providing core roles to Application Centers both in and outside of Japan

We are actively working to create new products and businesses that will become the seeds for growth. At LINTEC, the creation of new products and businesses is not limited to engineers with specialized technical skills. While the Research & Development Division plays a central role, we have also established organizations within the Business Administration Division that are dedicated to developing new products and businesses. We are pursuing further enhancement of the competitive edge of our existing businesses and the creation of new products and businesses in tandem, while making Companywide efforts to increase corporate value by resolving social issues.



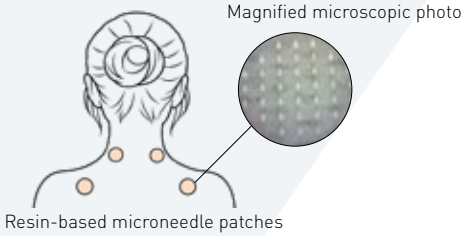
Toward Generating New Value Through the Creation of a Sustainable Society

The New Project Planning Office is engaged in creating new businesses with the aim of resolving environmental and social issues. In addressing challenges such as climate change and the promotion of resource circulation, we combine our technological assets with expertise from both inside and outside the Company to create both social and business value. In July 2022, we established the *Welsurt* purpose brand to bring these initiatives together under a unified framework. By leveraging our proprietary adhesive, release, and papermaking technologies, we are exploring new business opportunities through collaboration with universities, research institutions, and companies. At the same time, we are developing a framework that brings together technologies, human resources, and ideas and supports them consistently through commercialization. Specifically, we are working toward the commercialization of film heaters in the fiscal year ending March 31, 2027. We are also focusing on the high CO_2 absorption capacity of the moringa plant and are conducting joint verification studies with Kyushu University while exploring potential business models through collaboration with corporate partners. In addition, we have identified thermal management and the circular economy as priority areas for creating new businesses. In the area of the circular economy, in particular, we take a comprehensive view of the entire product life cycle, from bonding to disassembly and separation. Through the creation of businesses that contribute to resource circulation, we aim to help realize a sustainable society while enhancing corporate value over the medium to long term.

Welsurt
Wellbeing, sustainable and smart

Investigation of New Business Opportunities in the Healthcare Field

The Next Generation Innovation Group, which was established in April 2022, engages in creating new technologies and businesses from a medium- to long-term perspective that is not restricted by the existing businesses of adhesive products and specialty papers. As part of this approach, in August 2026 we announced the development of resin-based microneedle patches through collaboration with the Teikyo Heisei University Institute of Oriental Medicine. These patches provide gentle stimulation when applied to the skin, and a distinctive feature of this product is its proprietary design incorporating a structure with multiple fine resin microneedles. Application of the product has been confirmed to increase localized blood flow, and this increase is expected to contribute to the early alleviation of muscle tension, stiffness, and inflammation. We are considering its future commercialization as a new business opportunity in the healthcare field.



Printing and Industrial Materials Products

Business Strategy (Main Initiatives in Medium-Term Business Plan LSV 2030–Stage 2)

Printing & Variable Information Products Operations

- Sales growth and improved earnings in North America and Asia
- Efforts toward coexistence with the environment and the realization of a circular society
- Strengthening of quality, cost, and delivery and increased profits

Industrial & Material Operations

- Further functional enhancements and growth in sales of window film
- New product development and systems sales growth, contributing to solving the labor shortage and improving productivity
- Development and increased sales of digital print media
- Development of environmentally friendly products

Printing & Variable Information Products Operations

Printing & Variable Information Products Operations manufactures and sells adhesive papers and films for labels, among other products, that are used in various fields, and our share of the domestic market is approximately 30% for adhesive papers and approximately 60% for adhesive films. We are also working to expand our overseas network of production and sales sites, centered on Asia, while expanding business in the North American market, centered on our U.S. subsidiary MACTAC AMERICAS, LLC. Printing & Variable Information Products Operations is the largest business division, comprising approximately 46% of the Group's overall net sales.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Accelerating New Market Creation in Japan and Overseas

In the fiscal year ending March 31, 2027, we will strengthen initiatives aimed at maintaining and expanding our share of the Japanese market while creating new markets. This will lead to the further expansion of our existing share via measures including sales and promotion activities by formulating and then implementing sales strategies aligned with local characteristics. In the overseas market, we aim to discover new markets while expanding sales through methods that include the introduction of strategic products. We anticipate a further increase in demand for highly reusable and recyclable products that contribute to the realization of a circular society. In addition to accelerating the development speed of environmentally friendly products, we strive to generate demand for high-value-added environmentally friendly products, such as label materials that realize mono-material design.

Featured
Topic

Contribution to Enhancing Recyclability of Containers

An example of an environmentally friendly product that is being showcased at exhibitions and other venues is our mono-material label materials. We have achieved a shift to mono-material design (the use of a single material) by aligning the materials used for label facestock and adhesive with that of the adherend. This has enabled us to helping prevent the inclusion of contaminants that become a barrier to the recycling of materials, including PET-based containers that are adherends. There is an increasing need for reusable and recyclable plastic products due to the impact of increasing tensions in the Middle East, and we aim to propose such products going forward.

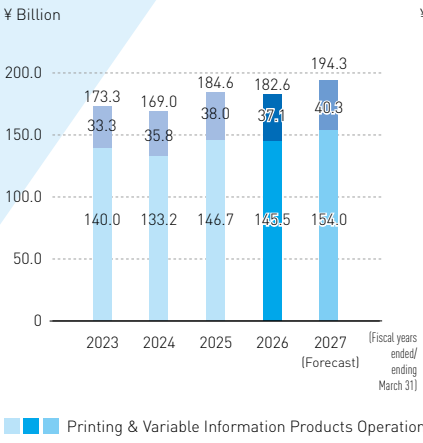
Q&A

Q&A in Response to Frequently Asked Questions from Investors

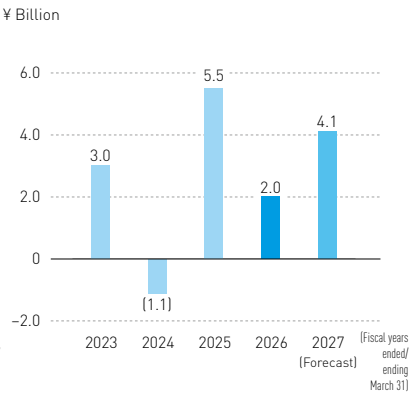
Please share how LINTEC is responding to the tensions in the Middle East.

A. We have implemented price adjustments for all adhesive products, starting from the July 1, 2026 shipment. The prices of adhesive papers have increased by 15% and adhesive films by 20%. If the disruption in the Middle East continues to deteriorate, we will consider further price revisions and will put all our effort into realizing stable supply. Following shortages of naphtha-derived products resulting from the tensions in the Middle East, there are concerns over the acceleration of label-free solutions in light of the trends toward reducing and eliminating plastic use across society as a whole. However, by reemphasizing the power, value, and functionality of labels, we will transform this risk into an opportunity and drive growth.

Net Sales by Segment



Operating Income (Loss) by Segment



Printing & Variable Information Products Operations　Industrial & Material Operations



Industrial & Material Operations

Industrial & Material Operations manufactures and sells a wide range of products, including window film that blocks solar radiation heat and UV rays and helps prevent the scattering of glass fragments in the event of window breakage by affixing to the inner side of glass in buildings and automobiles; decorative film for interior use; signage and advertising film for exterior use; adhesive products for motorcycles and automobiles with functions that include decorating and protecting the body; industrial-use adhesive tape used to affix components such as mobile devices; and highly efficient labeling machines that automatically affix labels.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Strengthening Market Competitiveness in Cross-Organizational Manufacturing

In the fiscal year ending March 31, 2027, we will continue our commitment to enhancing customer satisfaction and prioritizing quality, as set forth in the previous fiscal year. At the same time, we will work toward creating and delivering new services, including the development of new products that aim to enhance functionality in our core window film business and strengthened sales efforts targeting automobile dealerships and other channels. Specifically, we will strengthen our market competitiveness through cross-functional product development initiatives that integrate the efforts of the Sales Department, the Sales Promotion Department, and Group companies in Japan and overseas. As customer and market needs continue to evolve rapidly, we will accurately identify the products and services required by the market and translate those insights into swift product development, while also intensifying efforts to expand sales of existing products and expand the market.

Featured **Topic**

Demonstration of Heat Shielding Performance While Maintaining Transparency of Glass

In August 2026, we launched sales of a new window film product for buildings that contributes to heatwave measures. The thin metallic layer included in the film materials enhances the heat shielding performance and is capable of blocking approximately 53% of solar transmittance, which is the cause of rising temperatures inside buildings. While there is a metallic layer inside the film, this does not disrupt the brightness of the light streaming in through the window or the view outside. As a product capable of countering heat while maintaining the transparency of the glass, it has been widely proposed in projects that include condominiums, commercial facilities, and office buildings.

Q&A

Q&A in Response to Frequently Asked Questions from Investors

Please explain the earnings forecast predicting higher net sales but lower income for the fiscal year ending December 2026 for MADICO, the Company's U.S. subsidiary.

A. In the fiscal year ending December 31, 2026, net sales are expected to increase by approximately ¥2.4 billion year on year while operating income is projected to decline by approximately ¥200 million. This is related to MADICO's acquisition of sales rights for window film in the United States from an industry peer in January 2026. The fall in operating income is due to the application of U.S. accounting standards regarding inventory valuation in connection with the acquisition of sales rights; however, this is a transient factor. MADICO's safety film has been adopted by numerous U.S. states and is expected to continue driving higher sales volumes for products geared toward crime prevention.

Electronic and Optical Products

Business Strategy (Main Initiatives in Medium-Term Business Plan LSV 2030–Stage 2)

Advanced Materials Operations

- Continued capital investment and response to demand in growing electronics markets
- Development of new tapes, equipment, and proprietary processes related to packaging technologies in semiconductor back-end processes
- Establishment of mass production structures for CNT pellicles for EUV lithography equipment

Optical Products Operations

- Rollout of optical display-related adhesive products
- New product development and sales growth for optical clear adhesive for automobiles and other products
- Development of light-diffusing film
- Development of barrier film
- Sales expansion for surface processing optical film

Advanced Materials Operations

Advanced Materials Operations manufactures and sells products including semiconductor-related adhesive tape and equipment and multilayer ceramic capacitor-related tape. All our products boast high market shares, and we have created a unique position in the electronics industry. Orders for semiconductor-related adhesive tape, semiconductor-related equipment, and multilayer ceramic capacitor-related tape have all remained strong and are business sectors that have driven the performance of the Group in recent years.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Promoting the Establishment of a Sales Structure in Line with Increasing Product Demand

In the fiscal year ending March 31, 2027, we expect continued strong demand for high-performance semiconductors, including for HBM and AI data center applications, and we forecast further sales growth for semiconductor-related adhesive tape and equipment, as well as multilayer ceramic capacitor-related tape. We are striving to establish a supply structure that can meet the increase in demand by promoting the stabilization of raw material procurement and the reinforcement of our production structure. Additionally, at the same time as addressing various issues such as geopolitical risks and new environmental adaptations, we aim to ensure that our products continue to be selected by customers going forward by accurately understanding trends in technology advancements, including cutting-edge semiconductor packaging. We will advance the development of a sales structure to transform CNT pellicles for EUV lithography equipment, of which we are pursuing mass production, into a new pillar of the business.

Featured
Topic

New Processes That Contribute to Enhancing Yields for Semiconductor Chips

As miniaturization of semiconductor chips continues, the importance of the back-grinding process, in which the backside of a wafer is ground to achieve a flat surface, has been increasing in semiconductor manufacturing. However, in wafers where protruding electrodes known as bumps are formed on the circuit surface, creating a height difference between the central and peripheral areas, the application of a protective back-grind tape prior to wafer grinding can create a step at the wafer edge. This step may result in cracks, chipping, or fractures during the grinding process. We have developed a resin-coating process that eliminates this step by applying a UV-curable resin to the peripheral area where no bumps are present, thereby reducing post-grinding wafer thickness variations and the occurrence of cracks. We have also developed a new resin-coating system and commenced a full-scale order intake in April 2026.

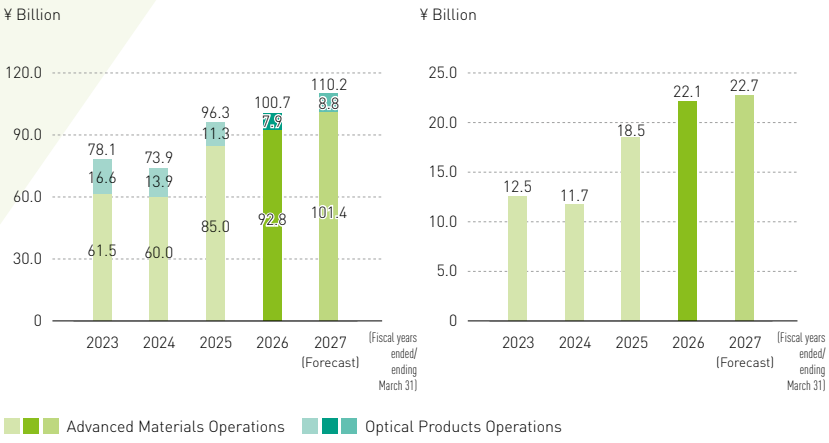
Q&A

Q&A in Response to Frequently Asked Questions from Investors

Please share the sales performance of the three major products in the fiscal year under review (fiscal year ended March 31, 2026).

A. Sales have remained strong for semiconductor-related tape due to the increasing demand related to AI, with a 13.2% year-on-year increase (compared with the fiscal year ended March 31, 2025), to ¥44.8 billion. For multilayer ceramic capacitor-related tape, sales have also remained strong due to robust demand for high-end products, such as data centers and smartphones, with a 13.7% year-on-year increase, to ¥23.9 billion. For semiconductor-related equipment, while both orders and deliveries for HBM manufacturing showed signs of recovery in the second half of the fiscal year sales declined 3.9% year on year, to ¥21.7 billion. Going forward, we anticipate high year-on-year growth in all products (fiscal year ending March 31, 2027).

Net Sales by Segment



Operating Income by Segment



Optical Products Operations

Optical Products Operations manufactures and sells optical display-related adhesive products by leveraging our expertise in the development of specialty adhesive agents and surface coating agents, our precision coating technology, and our high-performance production equipment. In addition to handling adhesive products for optical functional film that is essential for image displays in organic electroluminescence (EL) displays for products including smartphones, tablets, and large televisions, we are also striving to expand the lineup and sales for products that will become a new revenue base, such as high-barrier film.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Increasing Sales Volume Through Methods Including Discovery of New Applications

In the fiscal year ending March 31, 2027, we aim to expand sales of the Opteria series, optical functional materials that leverage our precision thin-film coating technology. In particular, we plan to prioritize the expansion of sales for high-barrier film for electronic paper, light-diffusing film for organic EL displays, optical clear adhesive (OCA) that does not use organic solvent, and anti-glare, low-reflection film. In our core optical non-carrier business, the trend toward reduced production of organic EL displays, driven by factors including rising raw material costs, remains a cause for concern. In response, we will continue initiatives such as revising our production structure and enhancing cost competitiveness. We are also exploring other applications and aim to increase sales volume both in Japan and overseas.

Featured
Topic

Receipt of Invention Awards for Three Patents in the Optical Electronics Field

We were awarded the 2025 Invention Encouragement Prize at the Kanto Regional Commendation for Invention, held by the Japan Institute of Invention and Innovation, for three patents related to adhesive sheets and coating film for cutting-edge optical displays. The technology related to these patents has been adopted in optical electronics-related products we have developed in our Opteria series. The Regional Commendation is divided into eight regions across Japan and commends the technicians, researchers, and developers who have created excellent inventions, concepts, and designs in each region. This was LINTEC's first time receiving this award. Going forward, we will develop and offer products that meet a wide range of social needs by integrating core technology at a high level.

Q&A

Q&A in Response to Frequently Asked Questions from Investors

Please share your aspirations for expanding sales of the Opteria series.

A. By combining our proprietary material design and development technologies for adhesive sheets, hard coat films, release films, and other products with our production technologies such as precision coating, we offer high-quality, high-performance, and high-value-added film products under the Opteria series. Applications span a wide range of fields, including automotive touch panels, smartphones, tablet devices, wearable devices, digital signage, and next-generation solar cells. We are advancing initiatives to expand our business by pursuing adoption and sales expansion in markets expected to achieve future growth.

Paper and Converted Products

Business Strategy (Main Initiatives in Medium-Term Business Plan LSV 2030–Stage 2)

Fine & Specialty Paper Products Operations

- Efforts to expand applications for oil-resistant paper
- Development and sales growth of high-performance papers as plastic alternatives
- Creation of high-value-added products
- Increase in profitability

Converted Products Operations

- Enhancement of overseas deployment of casting paper for synthetic leather
- Sales growth of casting paper for carbon fiber composite materials
- Development of new, early-stage products
- Promotion of environmentally friendly products

Fine & Specialty Paper Products Operations

Fine & Specialty Paper Products Operations manufactures and sells a wide range of paper products, including color paper for envelopes and colored drawing paper—for which we hold the top domestic market share—as well as special function paper such as dust-free paper used in clean rooms and oil-resistant paper used for packaging fried foods and other food items, high-grade printing paper with a distinctive texture, and construction-use paper used as backing paper for wallpaper. We are strengthening the development and proposal of products that address the growing demand in recent years for reducing and eliminating plastic use.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Promoting Measures Including the Creation of High-Value-Added Products

For the fiscal year ending March 31, 2027, initiatives in this segment focus on the goals of improving profitability, boosting sales volume, and creating new products. To enhance profitability, we will work to commence the full-scale launch of business reforms, implement price revisions, and ensure appropriate inventory levels, which got underway in the fiscal year ended March 31, 2025. To increase sales volume, we aim to promote a full transition from fluorine-based oil-resistant papers to fluorine-free alternatives by lowering production costs and improving quality for these high-demand products. Additionally, we will reinforce sales activities and other measures aimed at acquiring new customers in growth industries. On the product development front, we will leverage the equipment of Converted Products Operations to create high-value-added products. We will also strengthen collaboration with the Research & Development Division and production sites to accelerate the formulation and execution of new development themes with greater speed.

Featured
Topic

Strong Performance by Industrial-Use Specialty Papers

Clean paper, one of our industrial-use specialty papers, is showing a strong sales performance. Clean paper is a high-performance dust-free paper that controls the release of fine particles at the 0.1μm level. This is paper developed for use within clean rooms, which are controlled environments that only allow a certain level of dust, and offers the basic properties of paper (suitability for writing and printing) while also producing minimal dust. It is not only used for operating instructions, project management sheets, notebooks, and printing paper within clean rooms, but also for various industrial-use casting papers and interleaving, playing a key role in supporting high-tech industries through "paper."

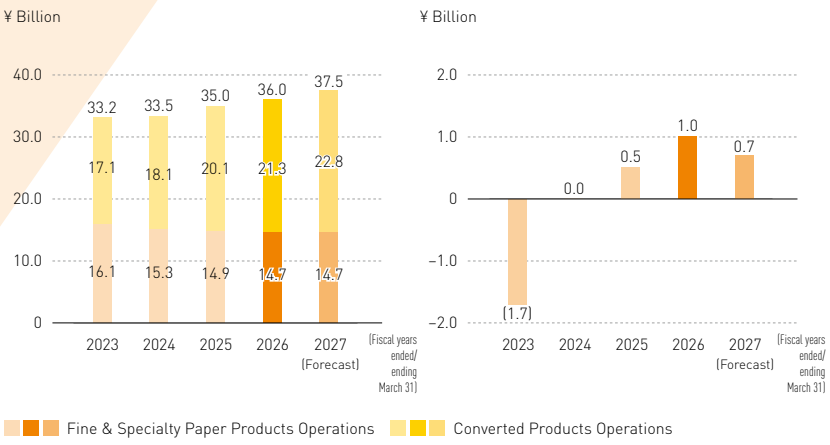
Q&A

Q&A in Response to Frequently Asked Questions from Investors

Will trends in reducing and eliminating plastic use become a business opportunity for Fine & Specialty Paper Products Operations?

A. Amid rising demand for reducing and eliminating plastic, LINTEC hopes to resolve various customer issues through paper. Under this concept, we launched our new specialty paper brand KAIKETSUSHI and are strengthening proposals aimed at creating new value. In addition to the previously mentioned oil-resistant paper, our specialty paper SUKEKAKE, which combines the natural, gentle texture of paper with superior pen-friendly and soft, translucent qualities, is another product that can contribute to resolving such issues. We also offer paper-based clear files that utilize the same transparency, thickness, and strength as plastic clear files, and as such, we are focusing on providing alternatives to these files.

Net Sales by Segment



Operating Income (Loss) by Segment

Fine & Specialty Paper Products Operations Converted Products Operations



Converted Products Operations

Converted Products Operations manufactures and sells release paper and film that protect the adhesive surfaces of various adhesive products by imparting not only releasability but also functions including water resistance, heat resistance, and abrasion resistance to paper and film substrates. We also provide casting paper used to impart patterns to synthetic leather and in the production of sheet-type carbon fiber composite materials.

Strategic Direction for the Fiscal Year Ending March 31, 2027

Strengthening Overseas Sales of Competitive Products

Although the market environment is expected to remain uncertain in the fiscal year ending March 31, 2027, we will focus on four priority initiatives to strengthen our business foundation: increasing sales volume, improving operating income, advancing environmental initiatives, and enhancing organizational resilience. In addition to strengthening the production system for release films, we will utilize the new coating facility that was introduced at the Komatsushima Plant (Tokushima Prefecture) in September 2025 to expand overseas sales of our competitive casting paper for synthetic leather and for carbon fiber composite materials. As part of our environmental response, we will actively promote solvent-free production processes that eliminate the use of organic solvents in the manufacture of release paper. We will further strengthen initiatives that respond to the needs of customers and society.

Featured
Topic

Expansion of Production Capacity for Casting Paper for Synthetic Leather

In September 2025, a new coating facility was introduced at the Komatsushima Plant, our principal production site for casting paper for synthetic leather. Featuring state-of-the-art capabilities for high-speed, high-precision coating, production capacity has increased to approximately 1.5 times the previous level. In recent years, synthetic leather has been attracting renewed attention across a wide range of industries due to its ease of processing, light weight, and functional performance. Demand for wider synthetic leather is increasing, particularly for automotive interior applications, and the new coating facility will enable us to increase the production of casting paper, especially production designed for wider casting paper. We will leverage this capacity expansion to drive sales growth for casting paper for synthetic leather in India, China, Europe, North America, and other markets.

Q&A

Q&A in Response to Frequently Asked Questions from Investors

What market trends are most closely linked to the performance of Converted Products Operations?

A. The answer differs by product category. General release paper for adhesive products tends to track with the market conditions of LINTEC's Printing & Variable Information Products Operations and Industrial & Material Operations, as it is often used in similar applications. Release paper for electronic materials and release film for optical-related products are linked to the market for smartphones and PCs. Demand tends to increase when new smartphone models are released. Casting paper for synthetic leather is influenced by production trends in sectors such as sports footwear and automobiles, while casting paper for carbon fiber composite materials is tied to demand in the sports and leisure industries as well as increases in aircraft production.